



PART NO. : TG110-5006N1RL

16PIN SMT ISOLATION MODULE FOR 10/100BASE-TX
IEEE802.3u APPLICATIONS

RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

OPERATING TEMPERATURE 0/+70°C

ELECTRICAL SPECIFICATIONS @25°C

URNS RATIO

P1-3:P16-14

1CT:1CT $\pm 3\%$

P6-8:P11-9

1CT:1CT $\pm 3\%$

OCL (100KHz,0.1Vrms,8mA)

P1-3,P6-8

350 μ H min

DCR P9-11,P14-16

0.9 Ω max

LL P1-3,P6-8

0.4 μ H max

Cw/w

35pF max

INSERTION LOSS

0.1-100MHz

-1.1dB max

RETURN LOSS

0.5-30MHz

-18dB min

40MHz

-15.5dB min

50MHz

-13.6dB min

60-80MHz

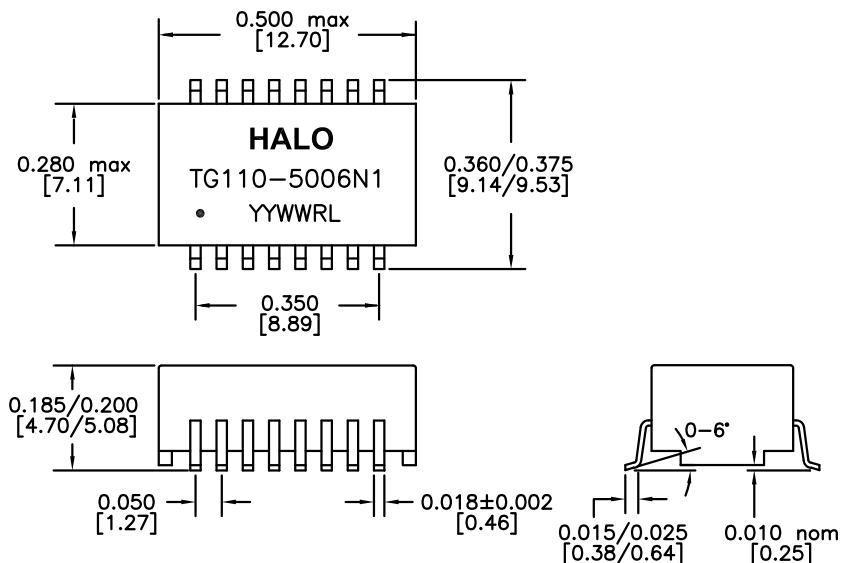
-12dB min

CROSSTALK 0.1-100MHz

-40dB min

ISOLATION

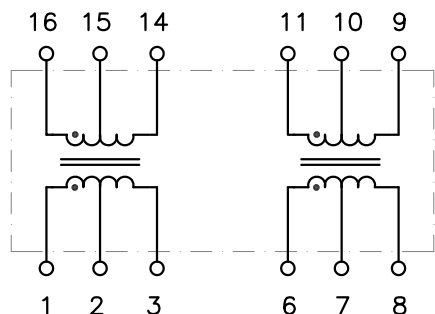
1,500Vrms



DIMENSIONS: Inch [mm]

CO-PLANARITY: 0.004 [0.10]

TOLERANCES: ± 0.005 INCH IF NOT SPECIFIED



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE ISOLATION TRANSFORMERS

FOR FAST ETHERNET

PART NO. TG110-5006N1RL

SCALE NONE

PAGE 1 OF 2

SIGNATURES

DRAWN LI ZHI ZHONG

CHECKED LEI KEONG

APPROVED PETER LU

FILE 110-5006RL.DWG

DATE

6/4/07

8/5/13

8/5/13

REV.

A

B

DESC.

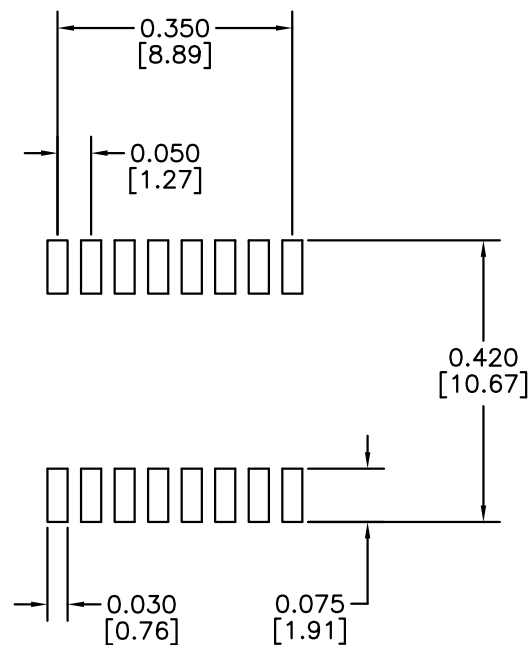
FIRST ISSUE

PROD. RELEASE

DATE

6/4/07

8/5/13



RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL

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FOR	FAST ETHERNET		DRAWN LI ZHI ZHONG	6/4/07	A	FIRST ISSUE	6/4/07
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